



Product Change Notification

Change Notification #: 115293 - 00

Change Title: Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x16 Low Profile 100HFA016LS,

Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x16 Standard 100HFA016FS

PCN 115293-00, Product Design, Product Material

Firmware Upgrade

Date of Publication: February 15, 2017

Key Characteristics of the Change:

Product Design, Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material: March 01, 2017

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Description of Change to the Customer:

Affected Product Code	Product Description
100HFA016LS	Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x16 Low Profile 100HFA016LS
100HFA016FS	Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x16 Standard 100HFA016FS

Overview of Changes:

Change 1: The firmware shall be updated as follows, (reference release notes for 10.2 and 10.3):

- A. OptionROM UEFI firmware version 0x29 shall be replaced with version 1.3.0.0.0
- B. OptionROM UNDI firmware version 0x29 shall be replaced with version 1.3.0.0.0
- C. OptionROM Config version 10.1.0.0.129 shall be replaced with version 1.0.1.0
- D. TMM firmware version 10.2.0.0.154 shall be replaced with version 10.2.1.0.3

Product Material Change Details:

Change 1: The firmware shall be updated as follows:

- A. OptionROM UEFI firmware version 0x29 shall be replaced with version 1.3.0.0.0
- B. OptionROM UNDI firmware version 0x29 shall be replaced with version 1.3.0.0.0
- C. OptionROM Config version 10.1.0.0.129 shall be replaced with version 1.0.1.0
- D. TMM firmware version 10.2.0.0.154 shall be replaced with version 10.2.1.0.3

Customer Impact of Change and Recommended Action:

Intel is not recommending additional qualification of these changes by customers.

There is no change to the adapter Intel Material Master (MM) numbers.

Please contact your local Intel Field Sales Representative if you have any questions about this change.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change MM# Rev	Post Change MM# Rev	Pre Change TA	Post Change TA	Pre Change AS	Post Change AS
100HFA016LS	948159	13	14	J10549-022	J10549-023	J10548-022	J10548-023
100HFA016FS	945671	3	4	J29320-003	J29320-004	J29321-003	J29321-004

PCN Revision History:

Date of Revision:

February 15, 2017

Revision Number:

00

Reason:

Originally Published PCN



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The products described in this document may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

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